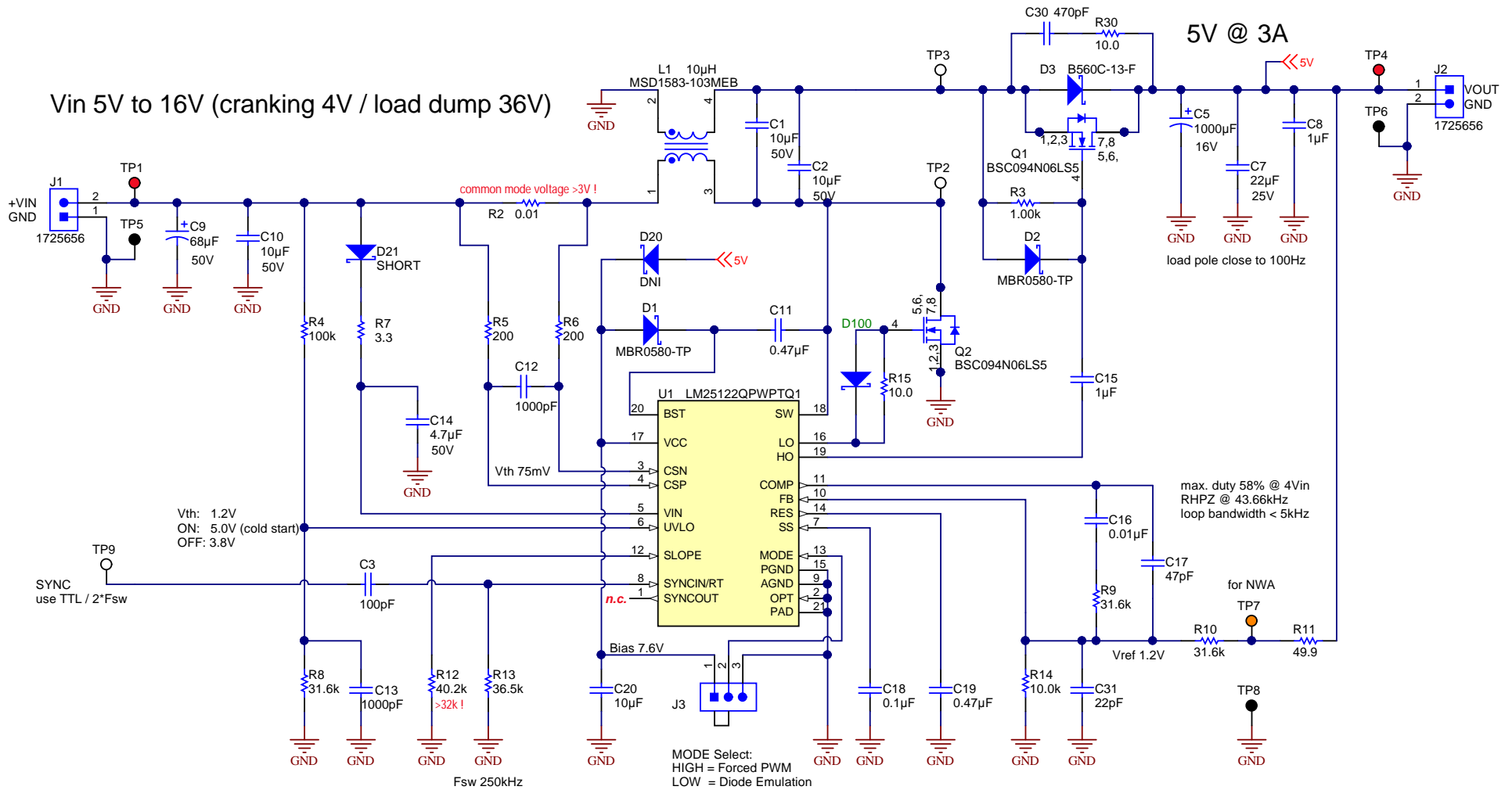


Vin 5V to 16V (cranking 4V / load dump 36V)



Revision History	
Revision	Notes
A	*** preliminary *** (cold start needs Vin > 5V)
B	*** tuned loop & gate drive

- 1) built on PCB 30232A
- 2) D100 backpaked R15

Orderable:	Designed for: Public Release	Mod. Date: 11/13/2017
TID #: N/A	Project Title: 15W sync SEPIC	
Number: PMP30331	Rev: B	Sheet Title:
SVN Rev: Version control disabled	Assembly Variant: [No Variations]	Sheet: 1 of 1
Drawn By:	File: PMP30331RevB_schematics.SchDoc	Size: A4
Engineer: B. Geck	Contact: http://www.ti.com/support	



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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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